

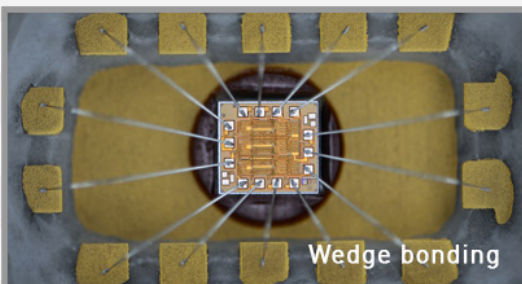


# HB100 Automatic Wedge & Ball Bonder

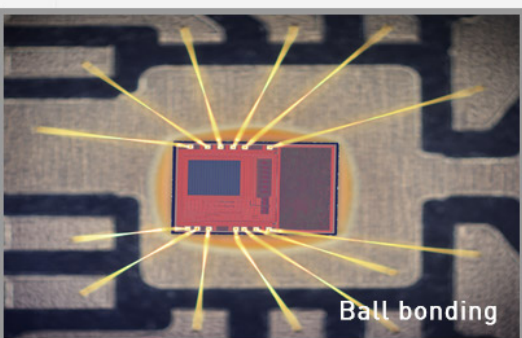
Motorized Z- X- Y- Axis & Bondhead Rotation



The HB100 is a new generation of automatic desktop wire bonders. It is suited for laboratories and small volume productions. It performs wedge- and ball-bonding with one bond head. The HB100 is very easy to handle with touch-screen and joystick. The software strongly supports the user with process guidance and bond assist features. The bonding technology is based on our popular semi-automatic bonders. It is completely engineered and manufactured in our German factory.



Wedge bonding



Ball bonding

- + Wedge and Ball Bonding with One Bond Head
- + Touch Screen Interface with 21" and Joystick Controller
- + Linear Motor Axis System
- + Deep and Wide Bond Access with large Working Area
- + Bond wires from 17µm to 75µm
- + Dual Camera System
- + Crash Prevention System for Z-Axis Touch Down
- + Broad range of Accessories like Heater Stages & Top Plates

# HB100 Automatic Wire Bonder for Wedge & Ball Bonding

## Technical Specifications

Bonding Method	Wedge-Wedge, Ball-Wedge & Ribbon- bonding
Bond head capability	One head for Wedge & Ball bonding, only tool change required
Speed	1 Wire in 3 sec
Gold wire diameter	17 - 75µm ( 0,7 - 3 mil )
Aluminium wire diameter	17 - 75µm ( 0,7 - 3 mil )
Ultrasonic system	63,3 kHz Transducer PLL Control (110kHz option)
Ultrasonic power	0 - 10 Watt
Bond time	0 - 5 sec.
Bond force	10 - 200 cNm
Bonding tool	1,58 Ø 19 mm length (0,0624" x 0,750")
Wire spool size	2"
Clamp Design	Deep Access 90° wire feed angle, 14mm Immersion depth
Wire termination	Bond Head Tear or Clamp Tear
Clamp movement	Motorized, Up & Down
Ball size control	Negative EFO, Software controlled
Dual camera	Detail View & Overview at the same time
Z-Drive & Resolution	Lead Screw Motor / 0,5µm
Motorized Z travel	100 mm (3,93")
X-Y Drive & Resolution	Linear motors / 0,1 µm
Motorized X & Y travel	90 mm (3,93")
Max. component width	400 mm (15,74")
X-Y-Z Axis control	Joystick
Screen size	21" Touchscreen
Software environment	Industrial PC with Windows 7
Heater Stage	90mm Ø surface / mechanical clamping (other sizes available)
Temperature controller	up to 200°C +/- 1°C
Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	620mm (24,4") x 750mm (29,5") x 680mm (26,7")
Weight	Net 72 kg
Industry Standards	CE standards

## Accessories:



Microscope



Bond Starter Kit



Vacuum Pump



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Specifications are subject to change without prior notice